

The listing of claims replaces the previous version, and the listing of claims:

LISTING OF CLAIMS

1.(currently amended) A plasma-enhanced processing apparatus, comprising;

a process chamber in which a substrate is processed,

a pumping system ~~that pumps~~ communicating with said process chamber for exhausting gas in the process chamber,

a gas-introduction system that introduces process gas into said process chamber,

a plasma-generation means that generates plasma in said process chamber by applying energy to said process gas,

a substrate holder that holds said substrate in said process chamber, and

wherein an opposite electrode disposed in the process chamber to face ~~facing to~~ said substrate held by said substrate holder ~~is provided,~~ and ~~the opposite electrode~~ including a main body, a front board disposed on the main body, and ~~comprises~~ a clamping mechanism that clamps the front board ~~to support said front board onto the main body so that the front board is pressed onto the main body to have a uniform thermal contact at a side opposite to a side where the plasma is generated.~~

2.(currently amended) A plasma-enhanced processing apparatus as claimed in claim 1, wherein, said opposite electrode ~~comprises a main body, and~~ includes a cooling mechanism that cools said front board via said main body.

3.(currently amended) A plasma-enhanced processing apparatus as claimed in claim 1, wherein, said clamping mechanism includes ~~clamps the periphery of said front board by~~ a clamping plate in surface contact with said front board to clamp a periphery of the front board.

4.(currently amended) A plasma-enhanced processing apparatus as claimed in claim 3, wherein~~+~~ said front board has a step at said periphery that is sandwiched by said main board and said clamping plate, and said clamping plate is flush with said front board.

5.(currently amended) A plasma-enhanced processing apparatus as claimed in claim 1, further comprising~~+~~ a protector covering a surface of said clamping mechanism, ~~wherein~~ so that said surface is not exposed to said plasma.

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6.(currently amended) A plasma-enhanced processing apparatus as claimed in claim ~~4~~ 5, wherein~~+~~ said clamping mechanism includes ~~clamps the periphery of said front board by~~ a clamping plate in surface contact ~~on~~ with said front board to clamp a periphery of the front board, and said protector is flush with said front board.

7.(currently amended) A plasma-enhanced processing apparatus as claimed in claim 6, wherein~~+~~ said front board is made of silicon poly-crystal or silicon mono-crystal.

8.(currently amended) A plasma-enhanced processing apparatus as claimed in claim 3, wherein~~+~~ said clamping plate is screwed on a member except said front board to press said front board onto said main body, ~~and~~ with screwing torque ~~is~~ of 1Nm or more.

9.(currently amended) A plasma-enhanced processing apparatus as claimed in claim 6, wherein~~+~~ said clamping plate is screwed on a member except said front board to press said front board onto said main body, ~~and~~ with screwing torque ~~is~~ of 1Nm or more.

10.(currently amended) A plasma-enhanced processing apparatus as claimed in claim 6, ~~wherein~~+~~~~ further comprising a sheet made of carbon ~~is~~ inserted between said main body and said front board.

11.(new) A plasma-enhanced processing apparatus as claimed in claim 1, wherein said clamp mechanism clamps said front board by pressure along a direction of thickness of the front board.

12.(new) A plasma-enhanced processing apparatus as claimed in claim 1, further comprising a sheet between the main body and the front board.

13.(new) A plasma-enhanced processing apparatus as claimed in claim 12, wherein said sheet is made of carbon.

14.(new) A plasma-enhanced processing apparatus as claimed in claim 2, wherein said cooling mechanism prevents increase of temperature of the front board in operation.

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15.(new) A plasma-enhanced processing apparatus as claimed in claim 1, wherein said opposite electrode further includes an insulation casing disposed around the main body, and said front board has a stepped portion at a periphery thereof, said clamping mechanism engaging the stepped portion to be flush with a surface of the front board and being fixed to the insulation casing.

16.(new) A plasma-enhanced processing apparatus as claimed in claim 15, wherein said clamping mechanism further includes a clamping plate engaging the stepped portion of the front board, and a screw for fixing the clamping plate from a lower surface thereof to the insulation casing.

17.(new) A plasma-enhanced processing apparatus as claimed in claim 16, further comprising an L-shaped protector covering the screw and at least a part of the clamping plate, said L-shaped protector being fixed to the insulation casing at a side thereof.

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IN THE DRAWINGS

i In Fig. 2, add a sheet 5' between a front board 5 and a main body 61, which is explained in paragraph 0043 of the specification.